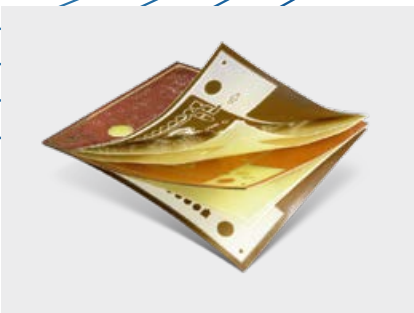


A Press for Multilayer Production

LPKF MultiPress S4

- In-house production of multilayer prototypes with rigid, rigid flex, flexible and RF materials
- Advanced intuitive graphical user interface with touch screen controls and guidance
- Up to five freely programmable temperature/pressure process steps
- Vacuum function and fume exhaust
- Stand-alone design; easily moveable on wheels

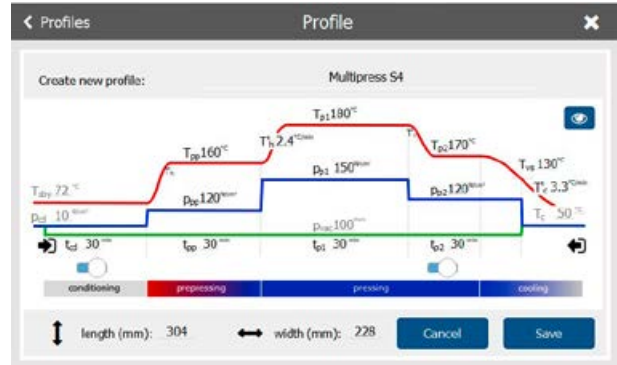


8-Layer Multilayer in Your Own Lab

A high packing density and the corresponding high number of circuits or additional tasks that need to be performed by the circuit board require a multilayer design of complex prototypes which can accommodate circuits in several layers.

The new concept with an intuitive graphical user interface offers an easy entry to multilayer production for a novice and opens up possibilities for setting up the process for next-generation materials. The three to five step process with different ramp-controlled temperatures and pressures can also utilize vacuum and rapid cooling.

The single-phase operation, built-in vacuum and hydraulic pump, connectivity, and predefined process setups for common materials make the stand-alone LPKF MultiPress S4 the most efficient system for multilayer pressing in your own lab. Any fumes or odors can be removed directly via an exhaust connection to the ventilation system.



LPKF MultiPress S4

Max. layout size	200 mm x 275 mm (7.8" x 10.8")
Max. laminating area	229 mm x 305 mm (9" x 12")
Min. laminating area	100 mm x 100 mm (4" x 4")
Max. laminating pressure	340 N/cm ² (493 PSI) at 229 mm x 305 mm (9" x 12")
Max. temperature	320 °C (608 °F)
Vacuum adjustment	Off, 0.1 – 0.9 bar (1.5 – 13 PSI)
Max. number of layers	8 (depending on material and layout)
Max. thickness of stack	4 mm (0.16")
Number of profiles	Unlimited, 5 preset
Dimensions (W x H x D)	500 mm x 980 mm x 500 mm (19.7" x 38.6" x 19.7")
Weight	205 kg (452 lbs)
Power supply	207 – 230 AC, 3 kW

Presented by:

